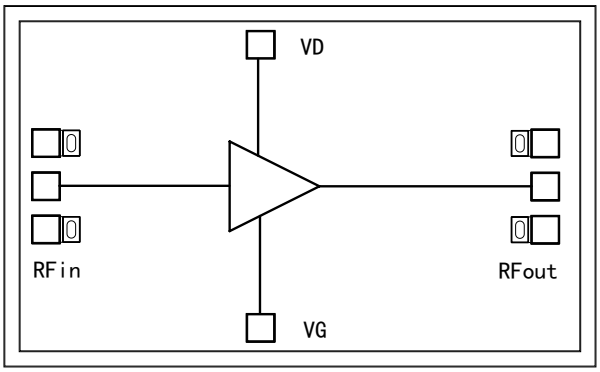
1. Description

- The M1721 is a 2-14GHz power amplifier manufactured using a 0.15μm gate-length gallium arsenide high electron mobility transistor (HEMT) process. The M1721 is grounded through backside metal via holes. All chips undergo 100% RF measurement.



M1721-PDS-F01

Figure 1. M1721 Functional Block Diagram

2. Applications

- TX/RX Modules
- Wireless Communications

3. Features

- Frequency Range: 2-14GHz
- Output Power (P_{SAT}): 26dBm
- Typical Gain: 9dB
- Typical Power Added Efficiency: 20%
- Small Signal Gain: 13dB
- Input Return Loss: -15dB
- Output Return Loss: -10dB
- Operating Bias: 8V /110mA
- Die Size: 3.35 x 1.40 x 0.10mm

4. Brief Typical Performance

Table 1. Brief Typical Performance

Parameter	14-19.5GHz	Units
Output Power	26	dBm
Power Gain	9	dB
Power Added Efficiency	20	%
Drain Dynamic Current	260	mA
Small Signal Gain	13	dB
Input/Output Return Loss	-15/-10	dB

- Test condition: Input signal and V_D Pulsed, Pulse width=4μs, Duty cycle=40%

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5. Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	8	V
Gate-Source Voltage	V_{GS}	-0.8	V
Maximum Input Power	P_{IN}	20	dBm
Maximum Forward Gate Current	$I_{G\ Max}$	1	mA
Storage Temperature Range	T_{STG}	-65 ~ +150	°C

6. Recommended Operating Conditions

Table 3. Recommended Operating Conditions

Parameter	Min.	Typ.	Max.	Units
Operating Temperature Range	-55	25	85	°C
Drain-Source Voltage Range, V_{DS}	-	8	-	V
Drain Bias Current, I_{DQ}	-	110	-	mA
Gate-Source Voltage, V_{GS}	-	-0.8	-	V

7. RF Characteristics (T_C = 25˚C)

Table 4. RF Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Units
Output Power	P_{SAT}	25.8	27	28	dBm
Power Gain	G_P	8	9	10	dB
Power Added Efficiency	PAE	18	20	27	%
Drain Dynamic Current	Id	230	260	270	mA
Small Signal Gain	Glin	12	13	14.2	dB

8. Typical Performance Curve

■ Small signal Characteristics Curve (T_C = 25˚C)

(V_D=8V, V_G=-0.8V, I_{DQ}=110mA, P_{IN}=-30dBm, CW)

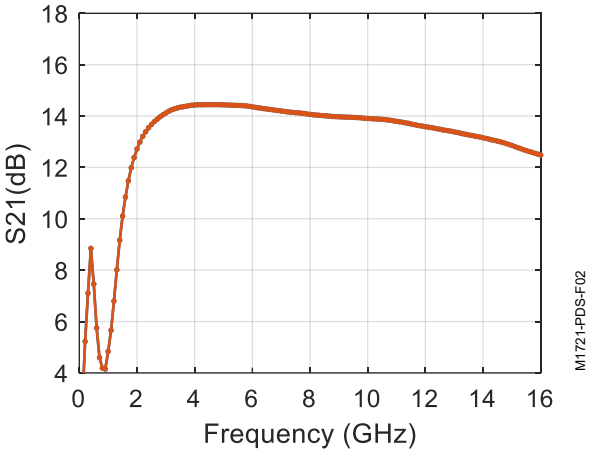


Figure 2. Small Signal Gain vs. Frequency

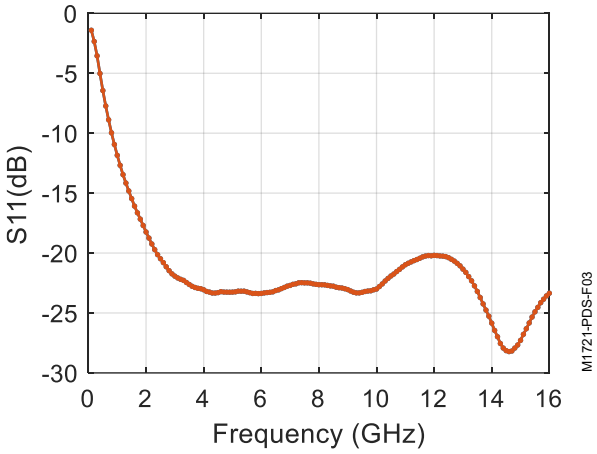


Figure 3. Input Return Loss vs. Frequency

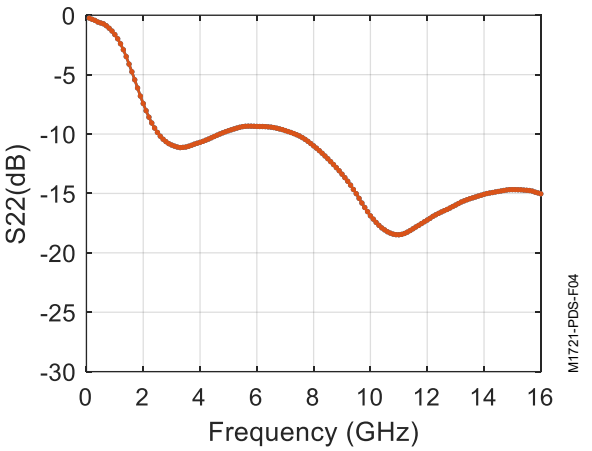


Figure 4. Output Return Loss vs. Frequency

■ Power Characteristic Curve

(V_D=8V, V_G=-0.8V, I_{DQ}=110mA, Pulse width=4μs, Duty cycle=40%)

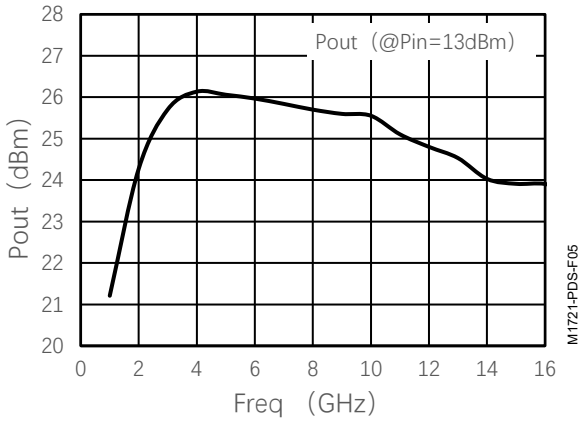


Figure 5. Output Power @ Pin=13dBm

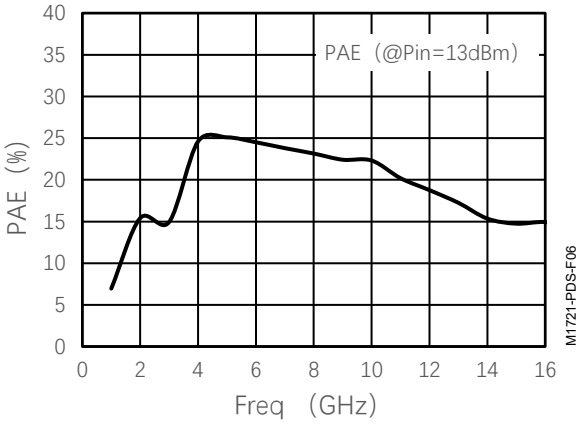


Figure 6. Power Added Efficiency @ Pin=13dB

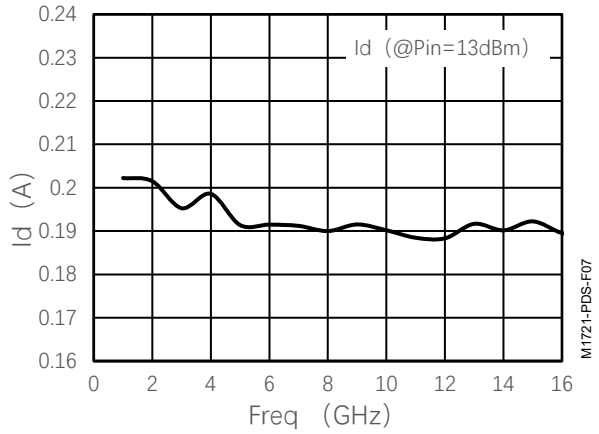


Figure 7. Drain Dynamic Current @ Pin=13dBm

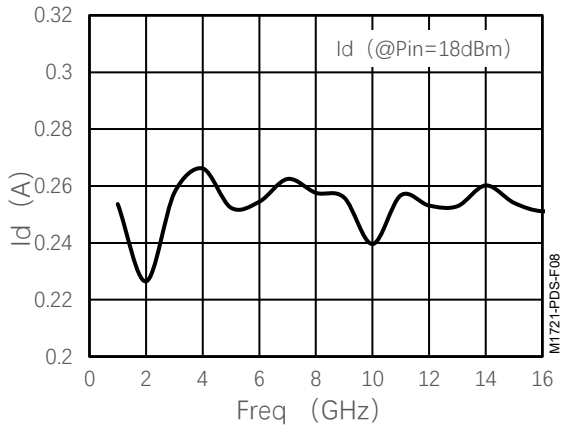


Figure 8. Drain Dynamic Current @ Pin=18dBm

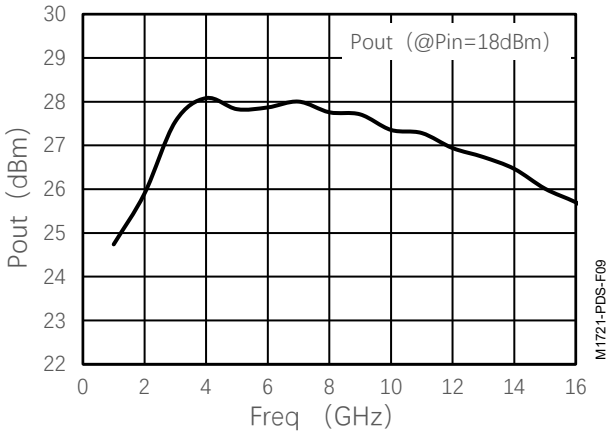


Figure 9. Output Power @ Pin=18dBm

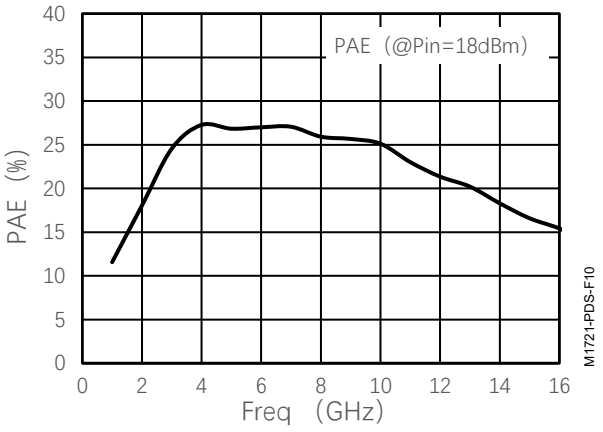
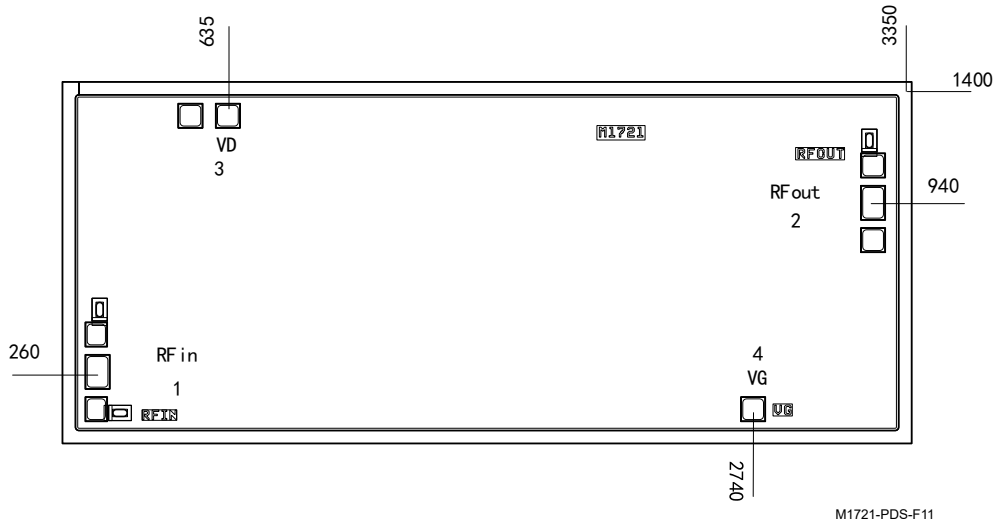


Figure 10. Power Added Efficiency @ Pin=18dB

9. Outline Dimensions



• Dimensions shown in micrometre

Figure 11. M1721 Outline Dimensions

Table 5. Pad Description

Pad	Symbol	Description
1	RF_{IN}	RF Input. 50Ω. DC blocking capacitor is not required.
2	RF_{OUT}	RF Output. 50Ω. DC blocking capacitor is not required.
4	VG	Gate Voltage. Bypass network required, refer to Figure 10.
3	VD	Drain Voltage. Bypass network required, refer to Figure 10.

10. Assembly Information

■ Assembly Diagram

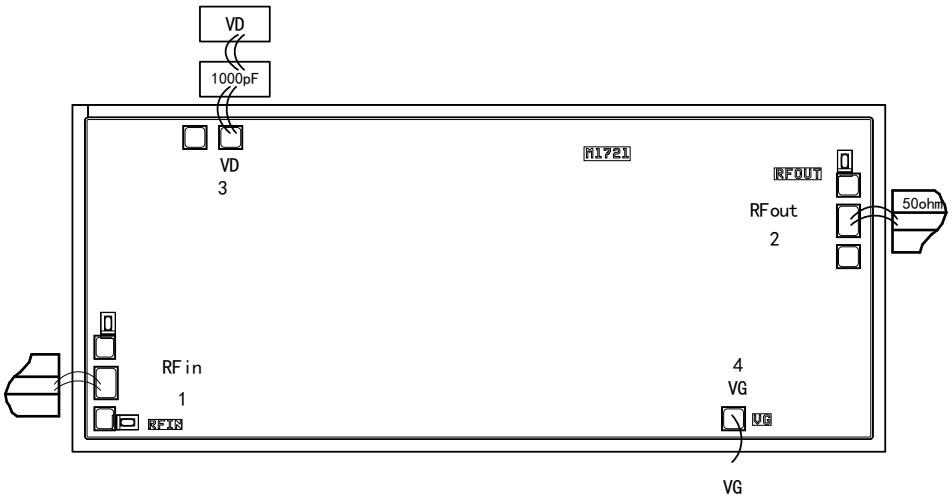


Figure 12. M1721 Assembly Diagram

- **Eutectic Die Attach:** It is best to use an 80% Au/20% Sn preform. Do not expose the chip to a temperature greater than 300°C for more than 30sec.
- **Wire Bonding:** RF bonds made with 1mil gold wire are recommended for the RF ports.

11. Handling Precautions

- **Storage**
  All bare dies ship in either Waffle or Gel Pak, which is an ESD protective container, and then sealed in an ESD protective bag. After opening the sealed ESD protective bag, all dies must be stored in a dry nitrogen environment.
- **Cleanliness**
  Handle the dies in a clean environment. Never use liquid cleaning systems to clean the dies.
- **ESD Caution**
  ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore proper ESD precautions should be taken to avoid performance degradation or loss of functionality.



12. Contact Information

For the latest specifications, additional product information, technical support and sales support, please contact:

- **Email:** RF.support@raytrontek.com
- **Web:** www.raytrontek.com

13. Disclaimer

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